RELIABILITY REPORT

FOR

MAX3272AEGP

PLASTIC ENCAPSULATED DEVICES

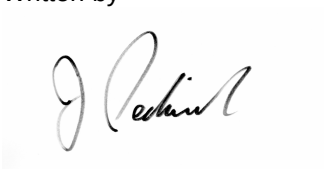
February 19, 2003

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Written by



Jim Pedicord
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Conclusion

The MAX3272A successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

Table of Contents

I. Device Description

A. General

The MAX3272A 2.5Gbps limiting amplifier accepts a wide range of input voltages and provides a constant-level output voltage with controlled edge speeds. Additional features include power detectors with programmable loss-of-signal (LOS) indication, an optional squelch function that mutes the data output signal when the input voltage falls below a programmable threshold, and an output polarity selector. This part exhibits excellent jitter performance and has low power dissipation.

The MAX3272A features current-mode logic (CML) data outputs that are tolerant of inductive connectors, and is available in a 4mm x 4mm QFN package. The MAX3272 is ideal for low-power, compact optical receivers.

B. Absolute Maximum Ratings

Item	Rating
Power-Supply Voltage (VCC)	-0.5v to +6.0V
Voltage at IN+, IN-	(VCC - 2.4V) to (VCC + 0.5V)
Voltage at SQUELCH, CAZ1, CAZ2,TH, CLOS	-0.5V to (VCC + 0.5V)
Voltage at LOS, LOS	-0.5V to +6.0V
Voltage at LEVEL	-0.5V to +2.0V
Voltage at OUTPOL	-0.5V to +6.0V
Current into LOS, LOS	-1mA to +9mA
Differential Input Voltage (IN+ - IN-)	2.5VP-P
Continuous Current at IN+, IN-	50mA
Continuous Current at CML Outputs (OUT+, OUT-)	-25mA to +25mA
Continuous Power Dissipation	1600mW
Storage Ambient Temperature Range (TSTG)	-55°C to +150°C
Operating Junction Temperature Range (TJ)	-55°C to +150°C
Die Attach Temperature	+400°C
Lead Temperature (soldering, 10s)	+300°C

II. Manufacturing Information

A. Description/Function:	+3.3V, 2.5Gbps Low-Power Limiting Amplifier
B. Process:	GST4-F60
C. Number of Device Transistors:	726
D. Fabrication Location:	Oregon, USA
E. Assembly Location:	Korea
F. Date of Initial Production:	January, 2002

III. Packaging Information

A. Package Type:	**20-Pin QFN (4x4)**
B. Lead Frame:	Copper
C. Lead Finish:	Solder Plate
D. Die Attach:	Silver-filled epoxy
E. Bondwire:	Gold (1.2 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	Buildsheet # 05-4001-0005
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard JESD22-A112:	Level 1

IV. Die Information

A. Dimensions:	66 x 62 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Au
D. Backside Metallization:	None
E. Minimum Metal Width:	Metal1: 1.2; Metal2: 1.2; Metal3: 1.2; Metal4: 5.6 microns (as drawn)
F. Minimum Metal Spacing:	Metal1: 1.6; Metal2: 1.6; Metal3: 1.6; Metal4: 4.2 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts: Jim Pedicord (Reliability Lab Manager)
Bryan Preeshl (Executive Director of QA)
Kenneth Huening (Vice President)

B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.

C. Observed Outgoing Defect Rate: < 50 ppm

D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 150°C biased (static) life test are shown in **Table 1**. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 9823 \times 45 \times 2}$$

(Chi square value for MTTF upper limit)

Temperature Acceleration factor assuming an activation energy of 0.8eV

$\lambda = 10.78 \times 10^{-8}$ $\lambda = 10.78$ F.I.T. (60% confidence level @ 25°C)

This low failure rate represents data collected from Maxim's reliability qualification and monitor programs. Maxim also performs weekly Burn-In on samples from production to assure reliability of its processes. The reliability required for lots which receive a burn-in qualification is 59 F.I.T. at a 60% confidence level, which equates to 3 failures in an 80 piece sample. Maxim performs failure analysis on rejects from lots exceeding this level. Maxim also performs 1000 hour life test monitors quarterly for each process. This data is published in the Product Reliability Reports (**RR-1M** & **RR-B3A**).

B. Moisture Resistance Tests

Maxim evaluates pressure pot stress from every assembly process during qualification of each new design. Pressure Pot testing must pass a 20% LTPD for acceptance. Additionally, industry standard 85°C/85%RH or HAST tests are performed quarterly per device/package family.

C. E.S.D. and Latch-Up Testing

The HD13-1 die type has been found to have all pins able to withstand a transient pulse of 800V, per Mil-Std-883 Method 3015 (reference attached ESD Test Circuit). Latch-Up testing has shown that this device withstands a current of ±250mA.

Table 1
Reliability Evaluation Test Results

MAX3272AEGP

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 150°C Biased Time = 192 hrs.	DC Parameters & functionality	45	0
Moisture Testing (Note 2)				
Pressure Pot	Ta = 121°C P = 15 psi. RH= 100% Time = 168hrs.	DC Parameters & functionality	77	0
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic process/package data.

Attachment #1

TABLE II. Pin combination to be tested. 1/ 2/

	Terminal A (Each pin individually connected to terminal A with the other floating)	Terminal B (The common combination of all like-named pins connected to terminal B)
1.	All pins except V_{PS1} 3/	All V_{PS1} pins
2.	All input and output pins	All other input-output pins

1/ Table II is restated in narrative form in 3.4 below.
2/ No connects are not to be tested.
3/ Repeat pin combination I for each named Power supply and for ground

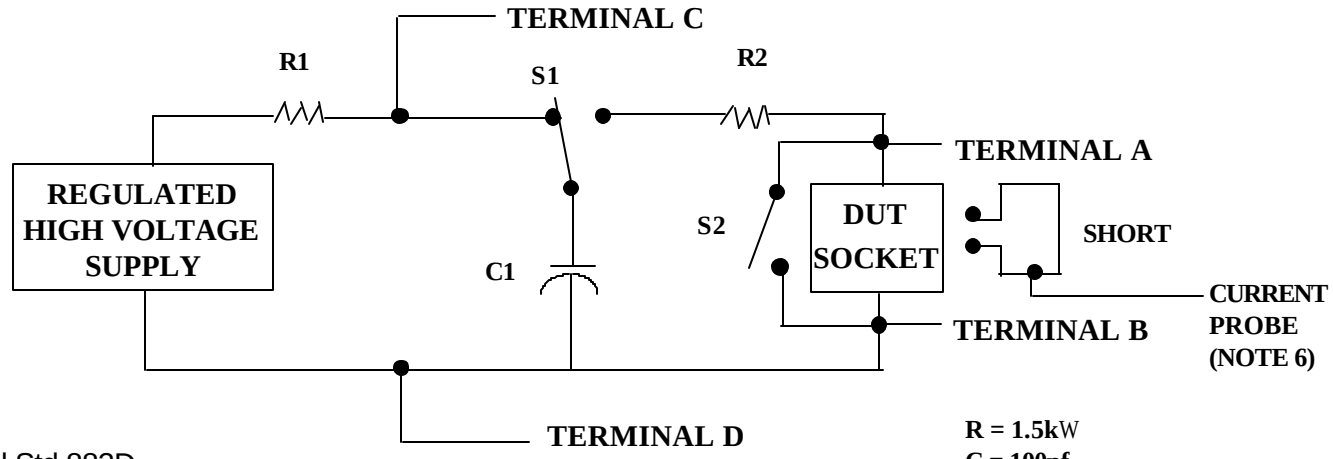
(e.g., where V_{PS1} is V_{DD}, V_{CC}, V_{SS}, V_{BB}, GND, $+V_S$, $-V_S$, V_{REF}, etc).

3.4 Pin combinations to be tested.

a. Each pin individually connected to terminal A with respect to the device ground pin(s) connected to terminal B. All pins except the one being tested and the ground pin(s) shall be open.

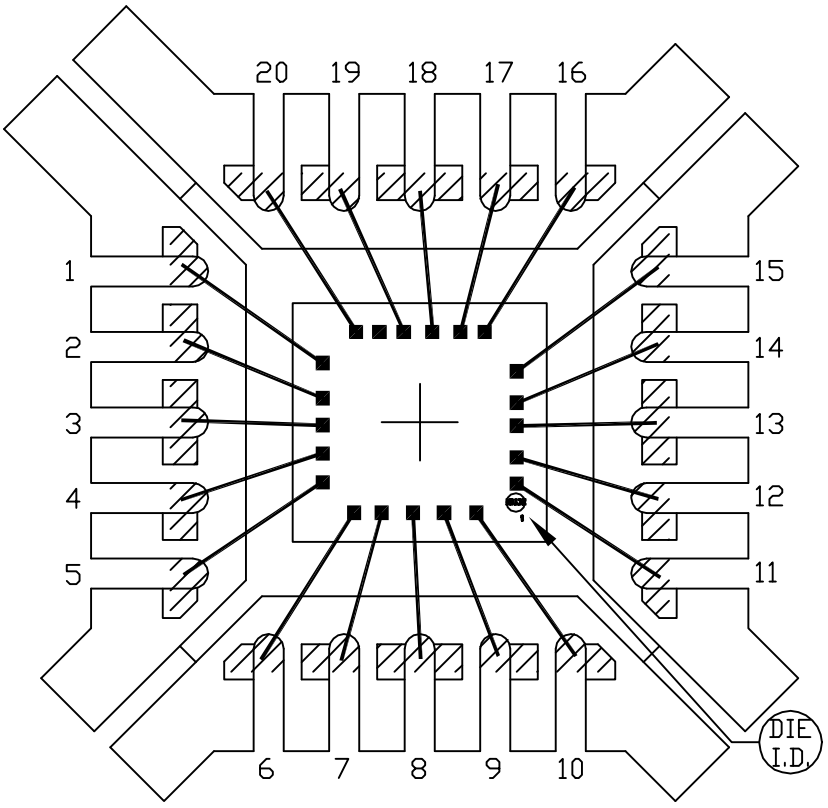
b. Each pin individually connected to terminal A with respect to each different set of a combination of all named power supply pins (e.g., V_{SS1}, or V_{SS2} or V_{SS3} or V_{CC1}, or V_{CC2}) connected to terminal B. All pins except the one being tested and the power supply pin or set of pins shall be open.

c. Each input and each output individually connected to terminal A with respect to a combination of all the other input and output pins connected to terminal B. All pins except the input or output pin being tested and the combination of all the other input and output pins shall be open.



Mil Std 883D
Method 3015.7
Notice 8

EXPOSED PAD PKG.



BONDABLE AREA

PKG. BODY SIZE: 4x4 mm

PKG. CODE: G2044-3		SIGNATURES	DATE	MAXIM CONFIDENTIAL & PROPRIETARY	
CAV./PAD SIZE: 91x91	PKG.			BOND DIAGRAM #: 05-4001-0005	REV: A
	DESIGN				